

Solder wire YS-RMA4-NP303

Product description

GENMA solder wire – our YS-RMA4-NP303 solder wire convinces with its extremely quick wetting properties. It is therefore ideally suited for automated iron-soldering, especially for spot soldering. Its quick and excellent wetting properties allow a rapid soldering process, also on difficult surfaces. Cleaning after soldering is not necessary.

Technical properties

	Specific value				Testing method
Diameter (mm)	0,15	0,3	0,5 / 0,6	0,8 / 1,0 / 1,2 / 1,6	
Weight spindle (g)	50	250	500	1000	
Flux type	ROL1, no clean				IPC J-STD-004B
Flux content (wt%)	4,50 ± 0,50				IPC-TM-650 2.3.34.1
Halide content (wt%)	0,07 ± 0,03				IPC-TM-650 2.3.35
Insulation resistance (Ω)	> 1 x 10 ¹² (40°C 90% rel. humidity)				IPC-TM-650 2.6.3.3
Insulation resistance (Ω)	> 1 x 10 ⁹ (85°C 85% rel. humidity)				IPC-TM-650 2.6.3.3
Migration	non				IPC-TM-650 2.6.14
Recommended solder tip temperature (°C)	330 - 350				
Recommended storage (°C)	0 - 40				

Alloys

Name	Alloy	Melting temperature range	Advantages
NP303	Sn 96,5 / Ag 3,0 / Cu 0,5 / SAC305	217 - 221	Standard alloy, excellent wetting

Compliance

Conform with RoHS-Regulation 2011/65/EU and 2015/863/EU

Contains no substances more than threshold (0,1%) according to REACH legislation EG Nr. 1907/2006 (SVHC-list - dated 26.02.2024)